DESCRIPTION:

The products are voltage opto-couplers in a plastic DIP8 package with different lead forming options. The device consists of a high-voltage output detector circuit.It is capable of directly driving gates of power MOSFETs or IGBTs. The products are widely used in supply for electronic circuit and drive solid state relay.

MAIN FEATURES

High isolation 5000 VRMS
Operating temperature range -40°C to 110°C
RoHS & REACH Compliance
HBM: H3A; MM: M4; CDM: C3
CQC approved
VDE approved
UL approved

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

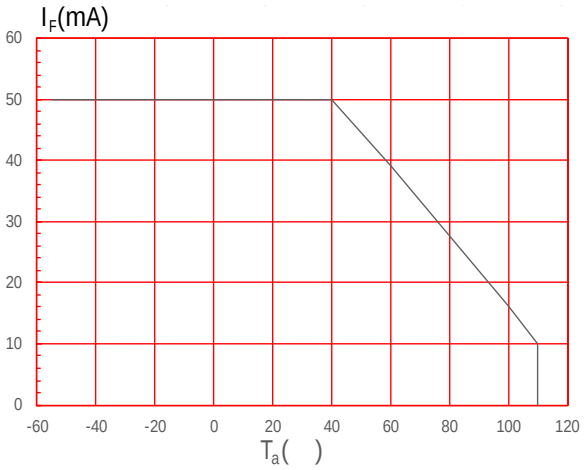
Input	Forward Current	I_F	50	mA
	Peak Forward Current	I_{FP}	1	A
	Reverse Voltage	V_R	6	V
	Power Dissipation		75	mW
Isolation Voltage			5000	Vrms
Operating Temperature		T_{opr}	-40~+110	

ELECTRICAL CHARACTERISTICS (Temperature=25°C)

Input	Forward Voltage	V_F	I_F=10mA	-	1.2	1.5	V
	Reverse Current	I_R	V_R=6V	-	-	1	μA
Output	Open Circuit Voltage	V_{OC}	I_F=10mA I_O=0mA	11	-	-	V
	Short Circuit Current	I_{SC}	I_F=10mA V_O=0V	5	-	-	μA
Transfer Characteristics	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	-	-	Ω
	Response Time	t_{on}	I_F=10mA	-	100	-	μs
		t_{off}		-	50	-	μs

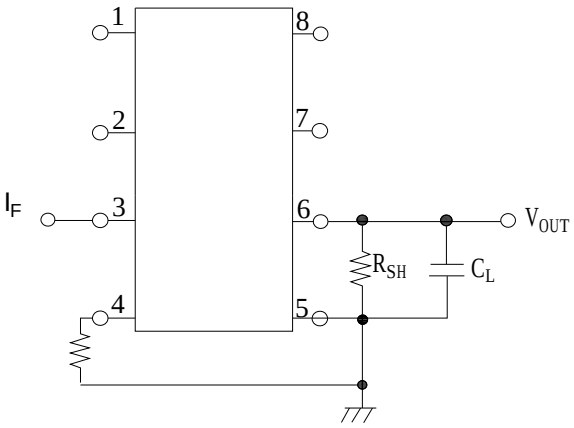
Characteristics Curves

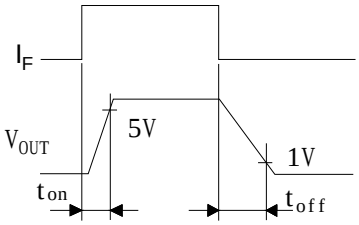
Max. Allowable LED Forward Current vs. Ambient Temperature



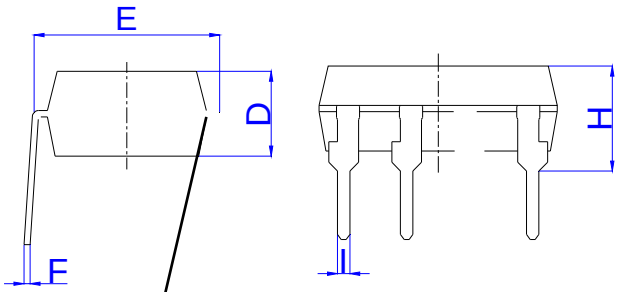
Forward Current vs. Forward Voltage

Test Circuits



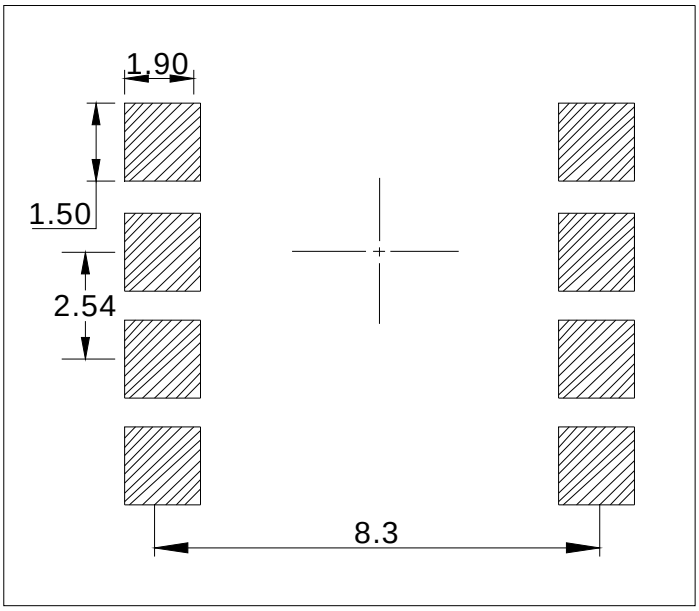


Package Dimension (Unit: mm)

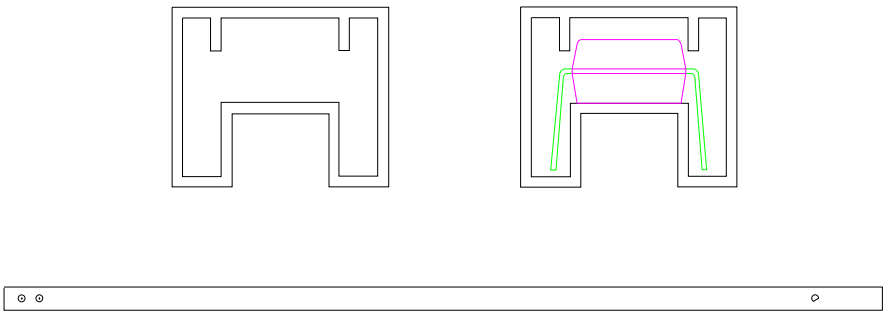


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)



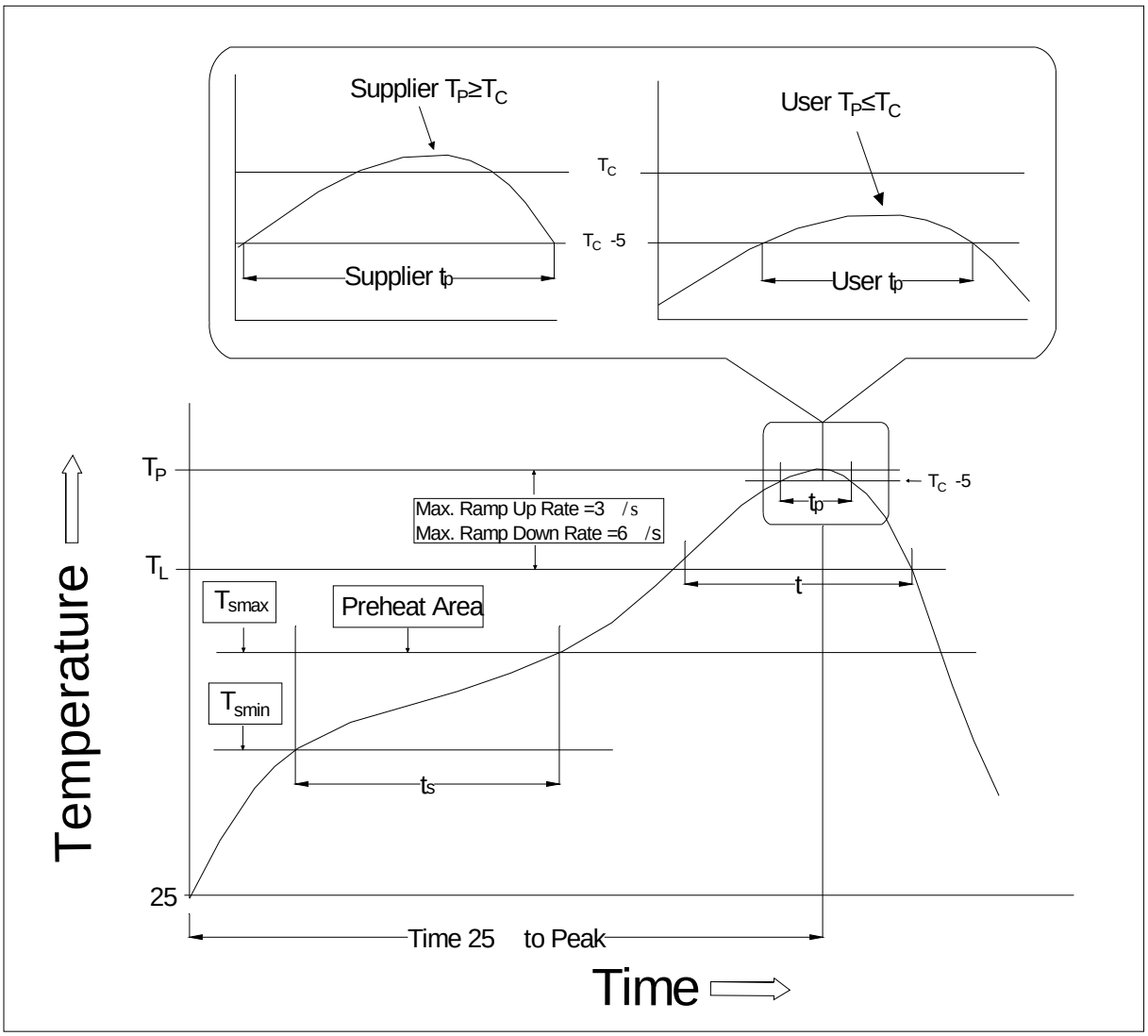
TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

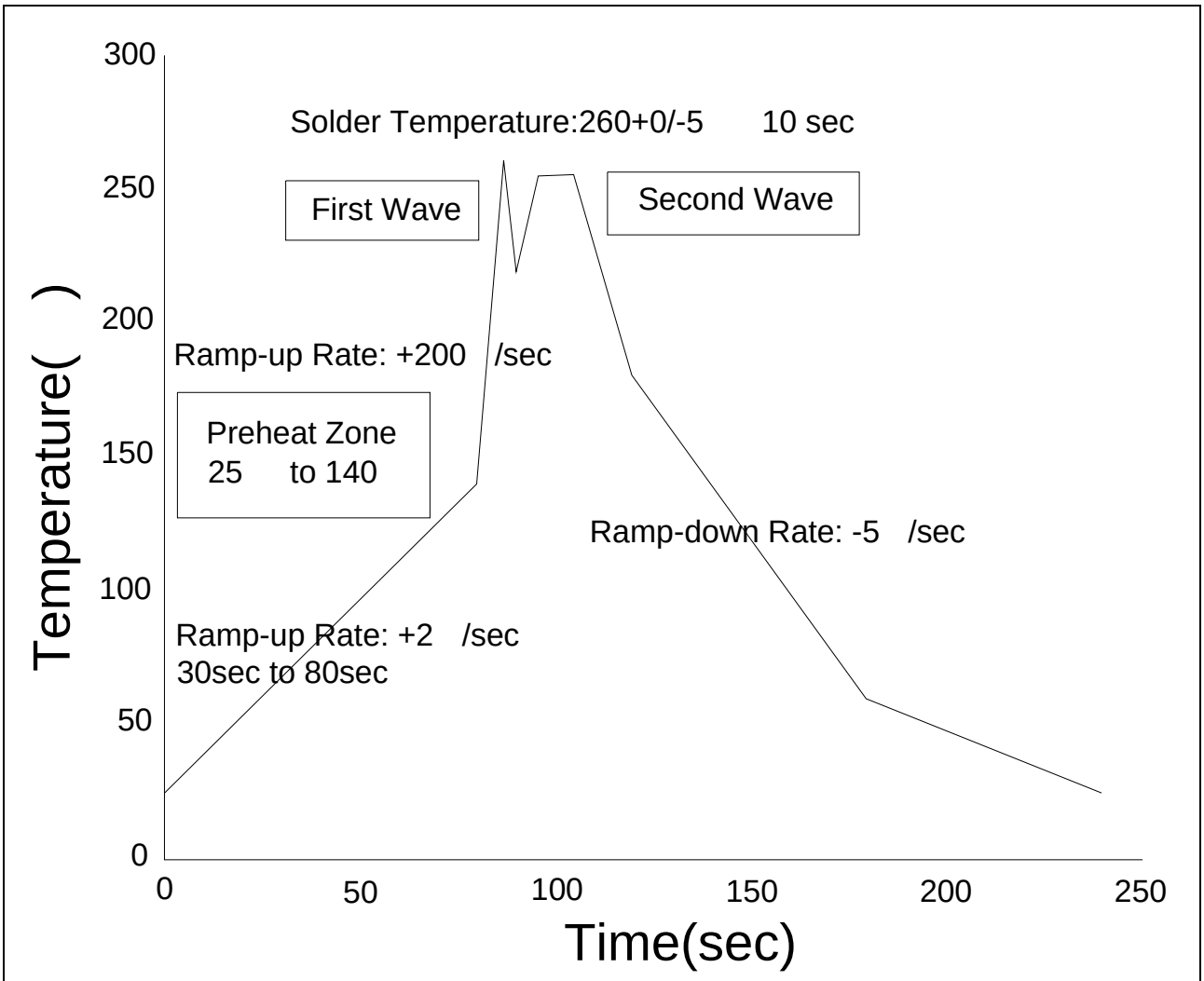
Ref.	Dimensions							
	Millimeters			Inches				
	Min.	Typ.	Max.	Min.	[illegible]	n.0	m, w .5	

REFLOW INFORMATION



Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	10 seconds	10 seconds
Ramp-down Rate (TP to TL)	3-6 /second	3-6 /second
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

WAVE SOLDERING



HAND SOLDERING BY SOLDERING IRON	
Soldering Temperature	360 ± 5
Soldering Time	3s max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1

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